

Organizational Chart

North America

Japan

Europe

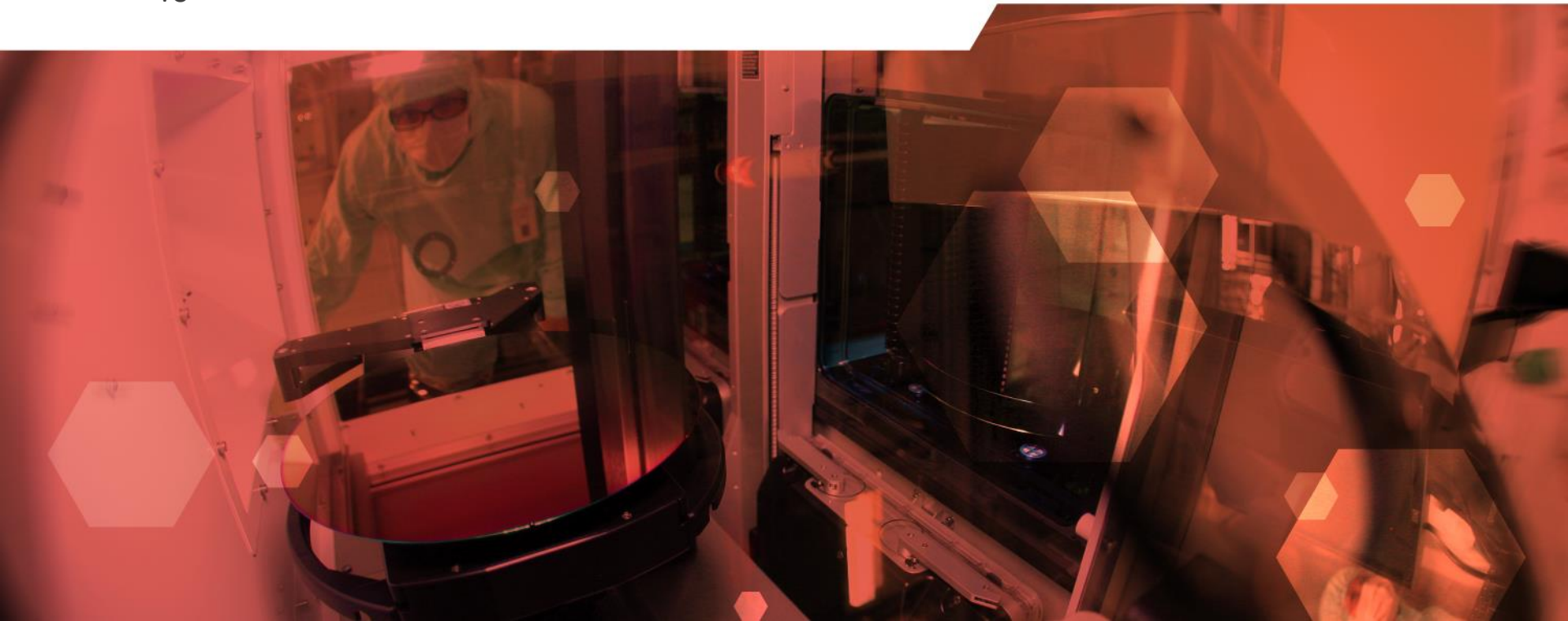
Last Updated: November 2017

v3

Korea

Taiwan

China



Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
EH&S				TCC		TCC	TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Traceability				TCC		TCC
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

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* In NA, Micropatterning is traditionally called Microlithography

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED		TCC			CFG	TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

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Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

* In NA, Micropatterning is traditionally called Microlithography

** 3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting

Vice-chair: Frank Petzold – Trustsec

Europe Chapter of Automation Technology Global Technical Committee

C: Christian Hoffmann – PEER Group

Europe Chapter of Liquid Chemicals Global Technical Committee

C: Jean-Marie Collard – Solvay Chemicals
C: Gordon Ferrier – Gordon F Consulting

Europe Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Alfred Honold – InReCon
C: Frank Petzold – Trustsec

Europe Chapter of Compound Semiconductor Materials Global Technical Committee

C: Arnd Weber – SiCrystal

Europe Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon
C: Frank Petzold – Trustsec

Europe Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant
C: Christian Hagendorf – Fraunhofer CSP

Europe Chapter of Gases Global Technical Committee

C: Jean-Marie Collard – Solvay Chemicals
C: Gordon Ferrier – Gordon F Consulting

Europe Chapter of Metrics Global Technical Committee

C: Alfred Honold – InReCon
C: Lothar Pfitzner – FhG IISB

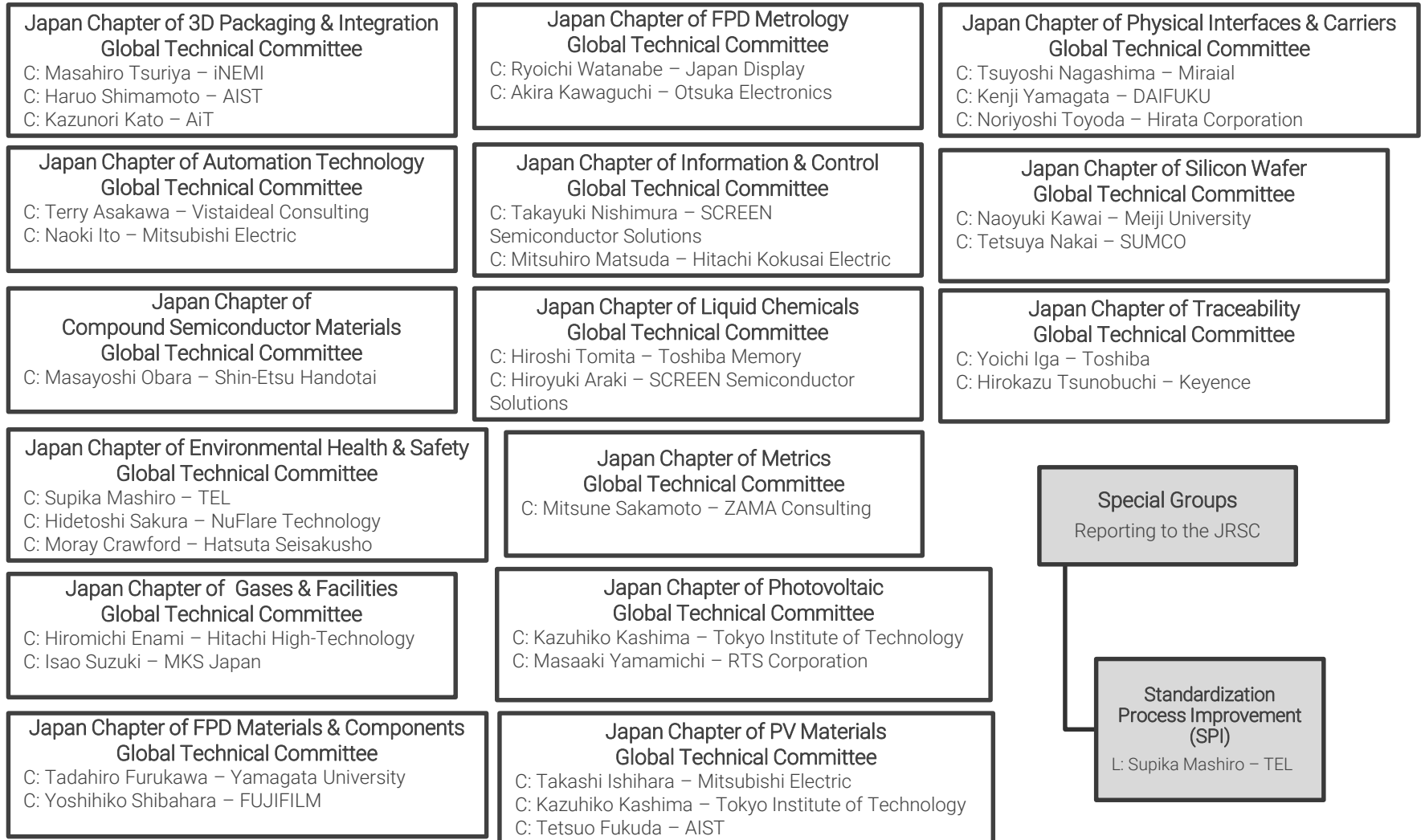
Europe Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – International Standards Consulting
C: Peter Wagner – Consultant
C: Fritz Passek - Siltronic

SEMI Japan RSC Organization

Co-Chair: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology

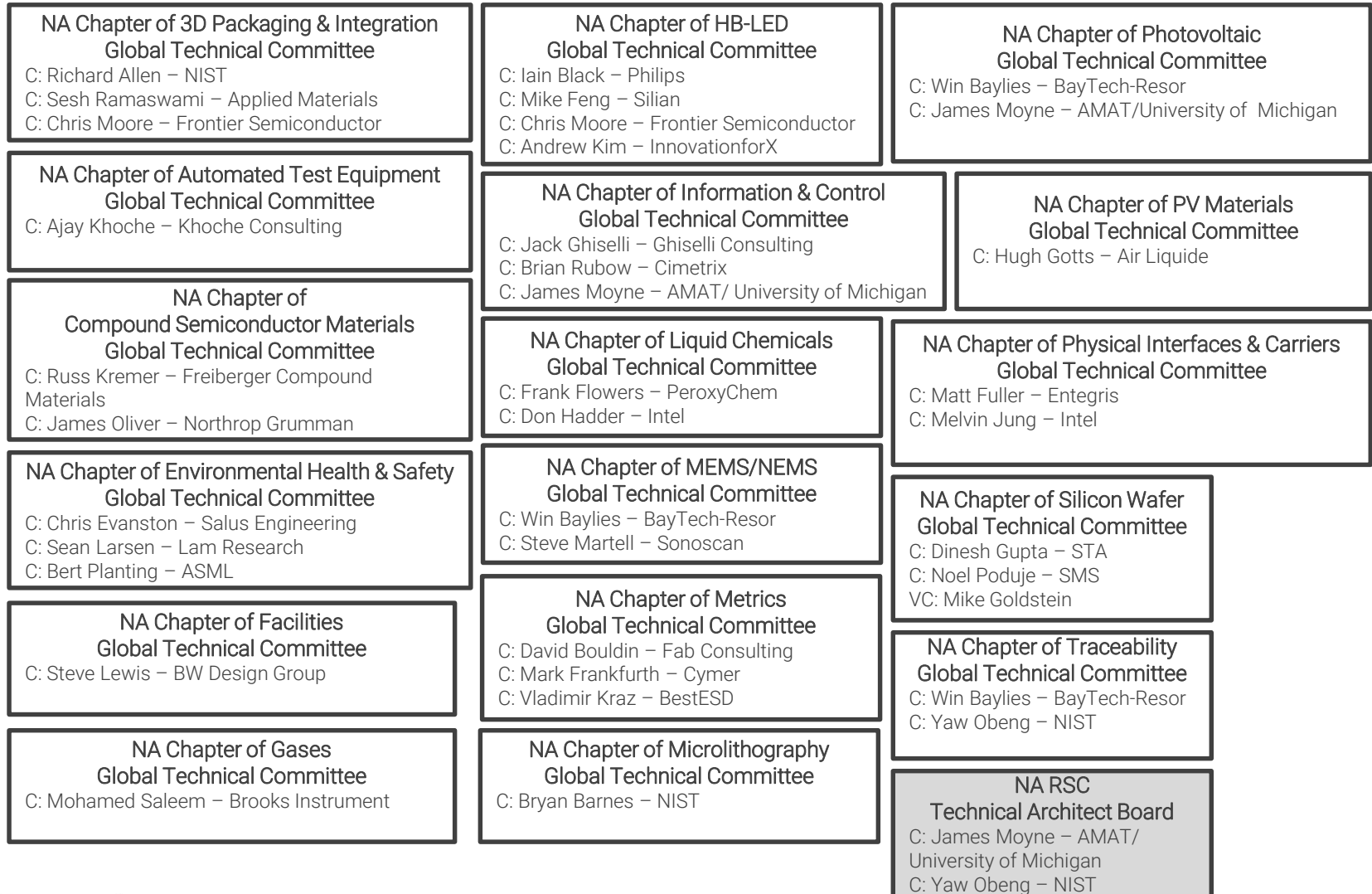
Vice-Chair: Supika Mashiro – TEL



SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix



SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

**China Chapter of Photovoltaic
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar

C: Jun Liu – China Electronics Standardization Institute

**China Chapter of PV Materials
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar

C: Jun Liu – China Electronics Standardization Institute

**China Chapter of HB-LED
Global Technical Committee**

C: Yong Ji – Guizhou Haotian Optoelectronics Technology

C: Weizhi Cai – San'an Optoelectronic

SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

**Korea Chapter of Facilities
Global Technical Committee**
C: Kwang Sun Kim – KUT

Korea HB-LED CFG
L: HyeongSoo Park – SEMES
L: Jong Hyeob Baek – KOPTI

**Korea Chapter of FPD Materials & Components
Global Technical Committee**
C: JongSeo Lee – Dell
C: Il-Ho (William) Kim – Light Measurement Solution

**Korea Chapter of Information & Control
Global Technical Committee**
C: Hyungsu Kim – Doople
C: Chul Hong Ahn – SK hynix
C: Gun Woo Lee – Lam Research

**Korea Chapter of FPD Metrology
Global Technical Committee**
C: JongSeo Lee – Dell
C: Il-Ho (William) Kim – Light Measurement Solution

SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

Taiwan Chapter of 3D Packaging & Integration Global Technical Committee

C: Wendy Chen – King Yuan Electronics
C: Chien-Chung Lin – ITRI
C: Roger Hwang – ASE

Taiwan Chapter of Flat Panel Display Global Technical Committee

C: Mike Yao – CMS/ITRI
C: Jia-Ming Liu – TDMDA

Taiwan Chapter of Automation Technology Global Technical Committee

C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI
C: Gwo-Sheng – ITRI/CMS
C: C.S. Wu – MIRDC

Taiwan Chapter of Information & Control Global Technical Committee

C: Robert Chien – TSMC

Taiwan Chapter of 3D Packaging & Integration Global Technical Committee

C: Wendy Chen – King Yuan Electronics
C: Chien-Chung Lin – ITRI
C: Roger Hwang – ASE

Taiwan Chapter of Photovoltaic Global Technical Committee

C: B. N. Chuang – CMS/ITRI
C: J.S. Chen – TeraSolar
C: Ray Sung – UL Taiwan

Taiwan Chapter of Environmental Health & Safety Global Technical Committee

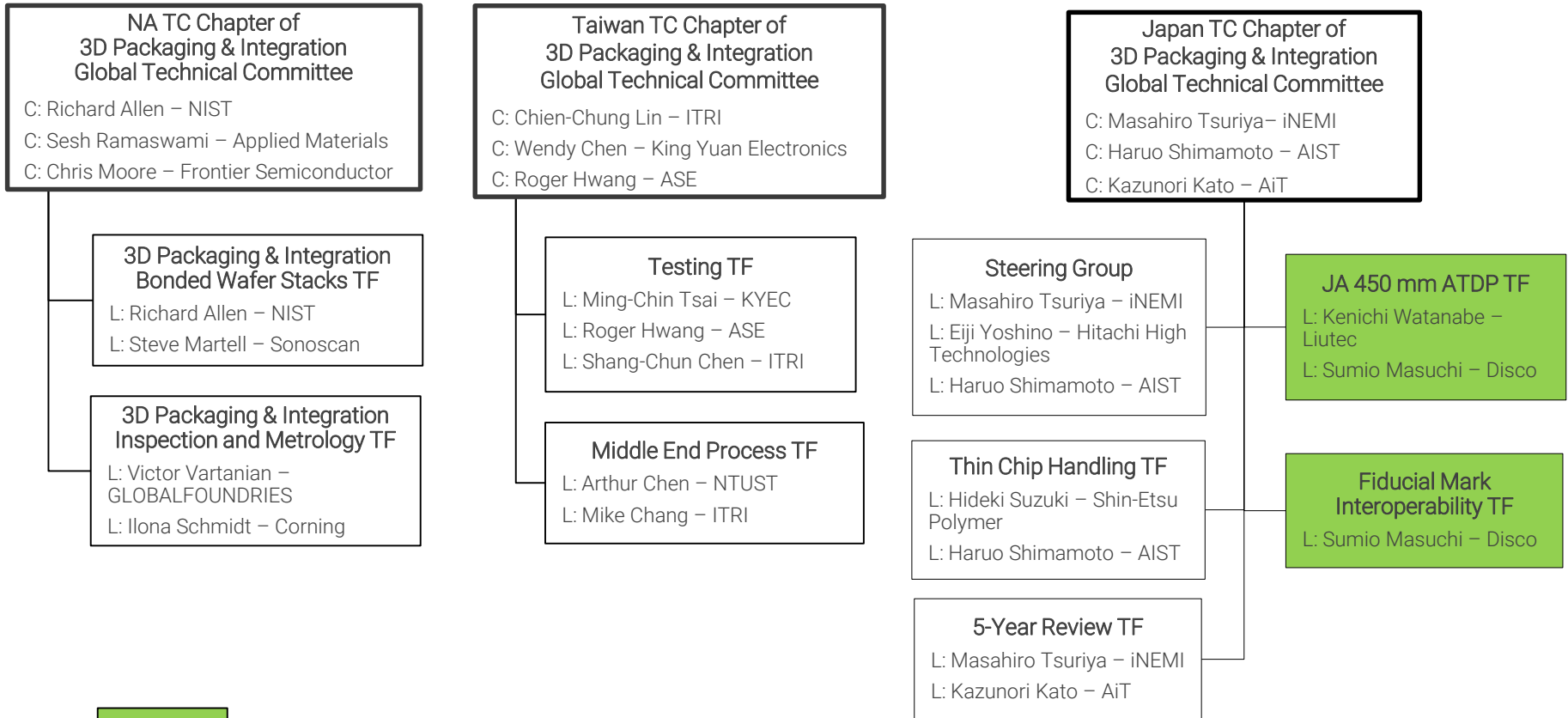
C: Shuh-Woei Yu – SAHTECH
C: Fang-Ming Hsu – TSMC


ISC Taiwan Advisor

Tzeng-Yow Lin – CMS/ITRI

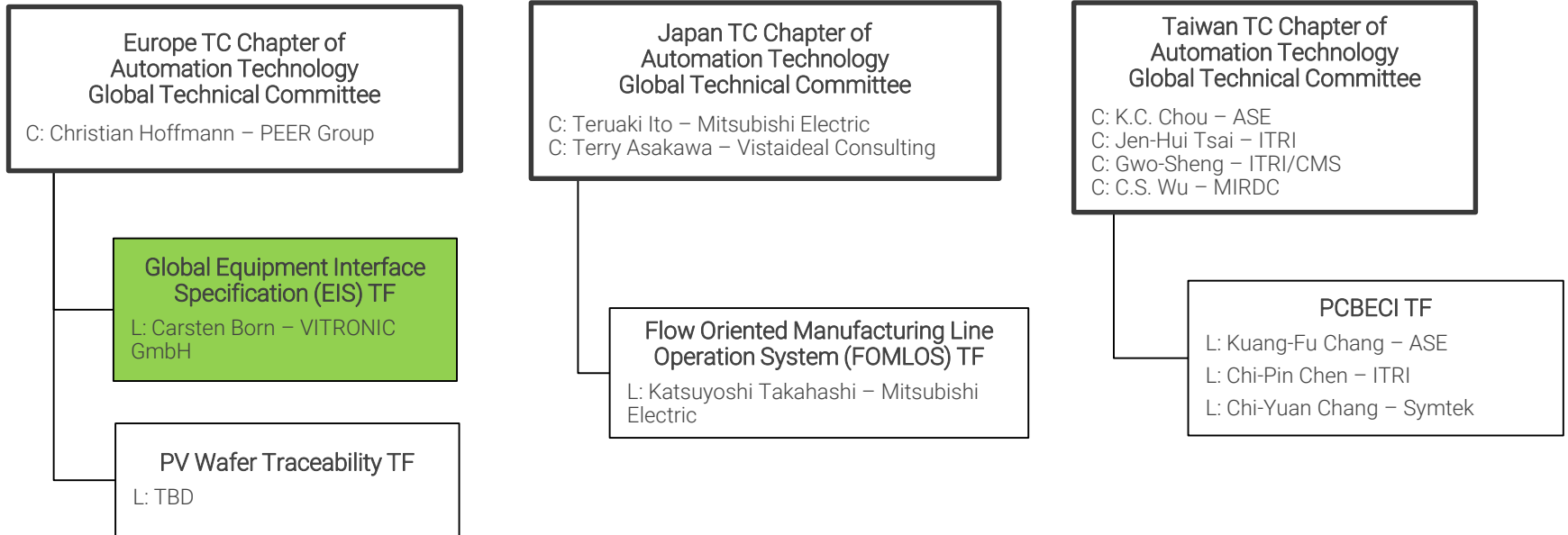
Organization of Each TC Chapter


3D Packaging & Integration (3DP&I) Global Technical Committee



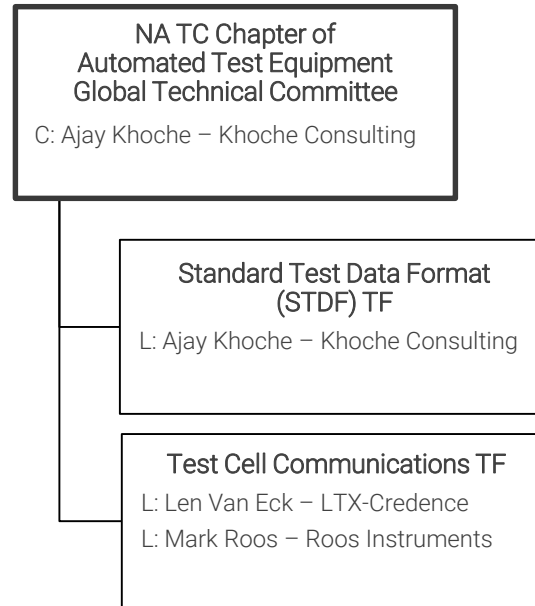
 = Global Task Force

Automation Technology (AT) Global Technical Committee

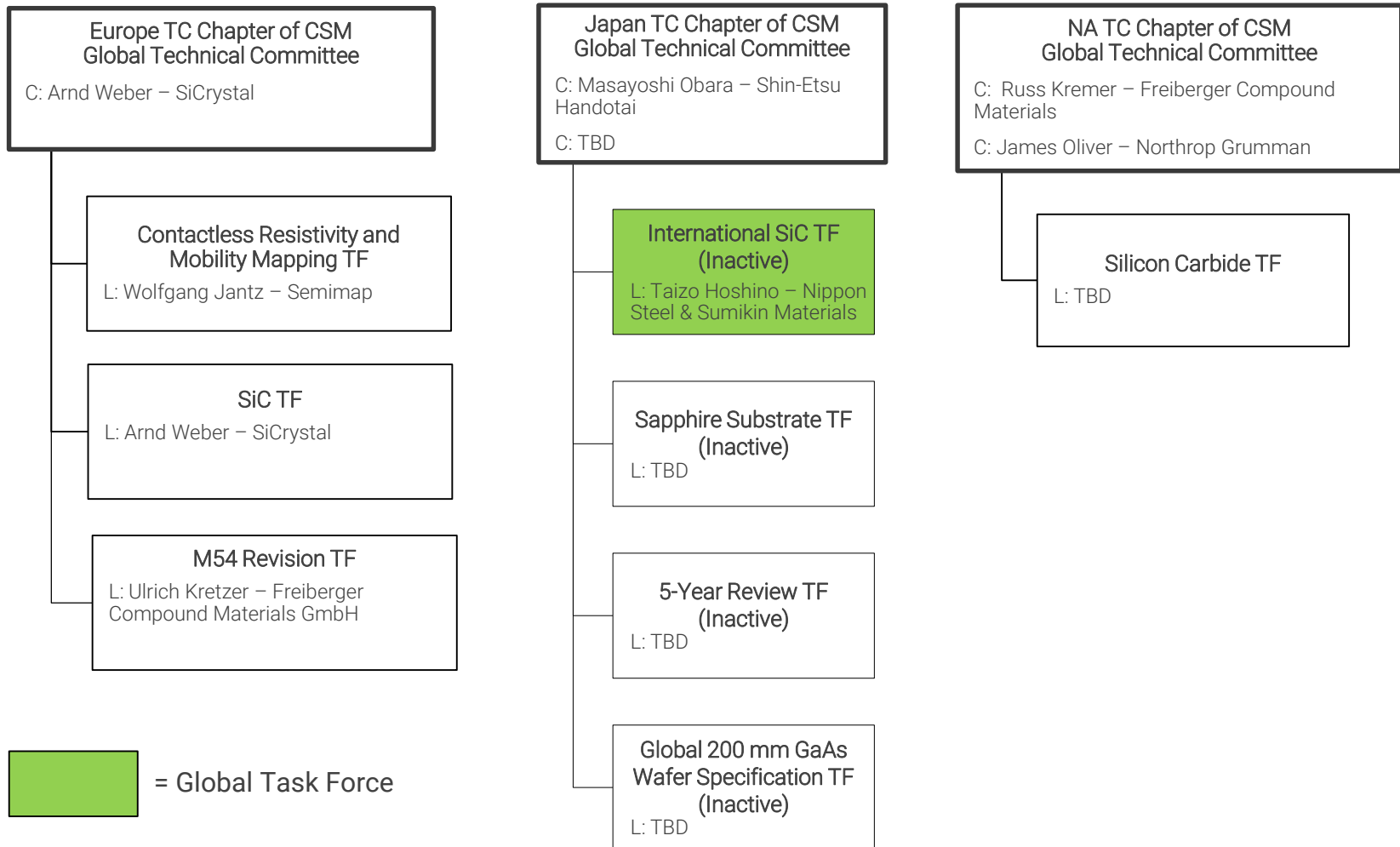


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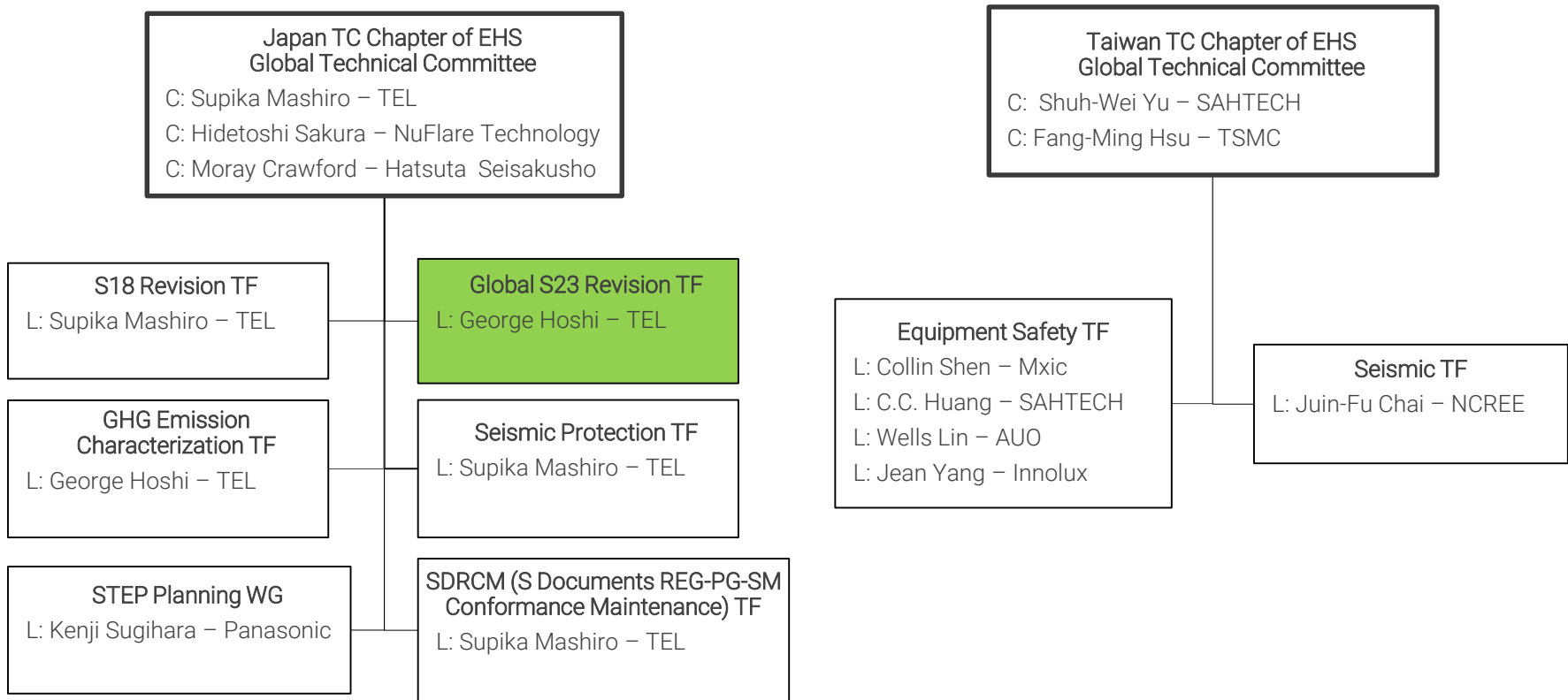
Automated Test Equipment (ATE) Global Technical Committee




Compound Semiconductor Materials (CSM) Global Technical Committee

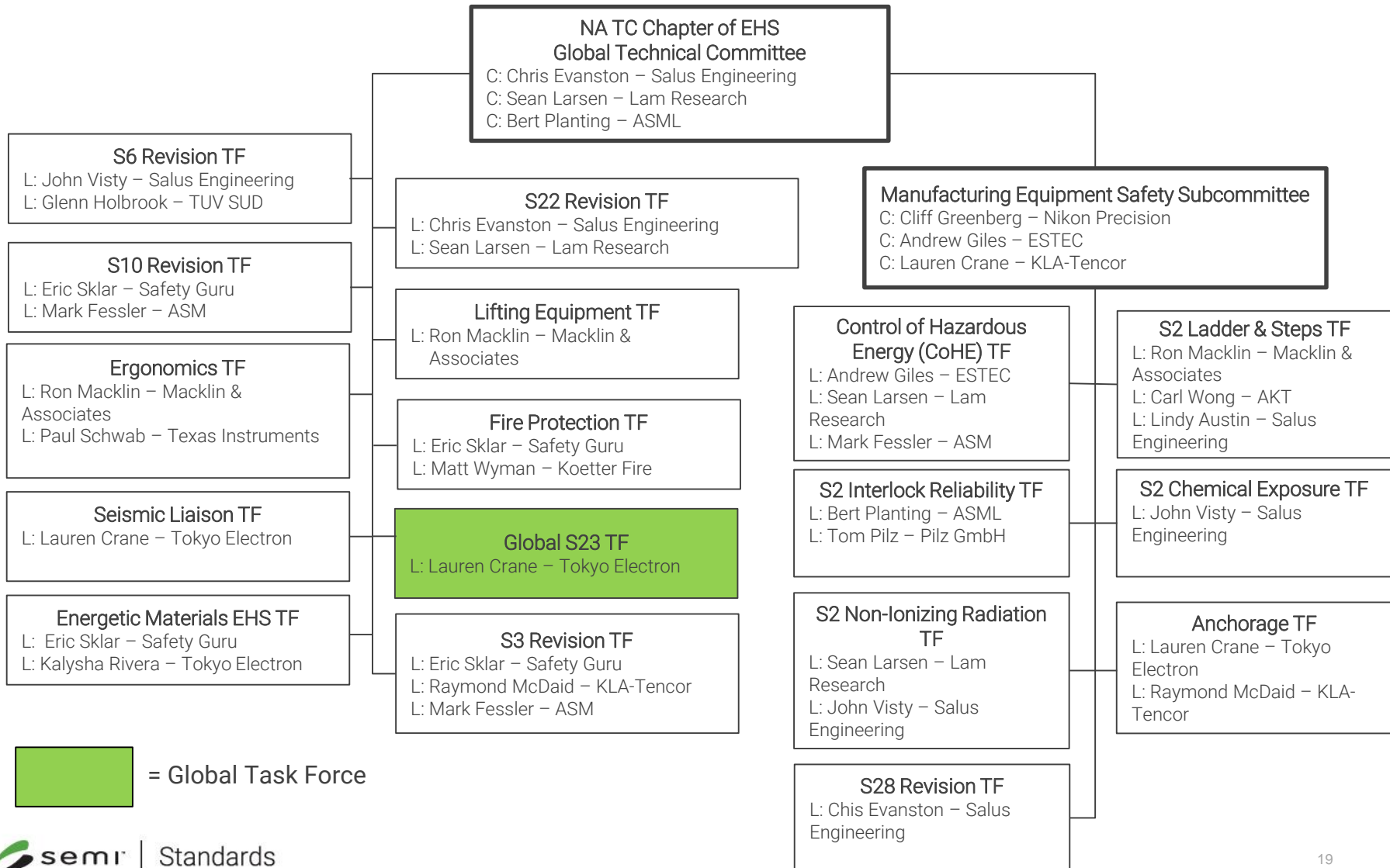


Environmental, Health & Safety (EH&S) Global Technical Committee



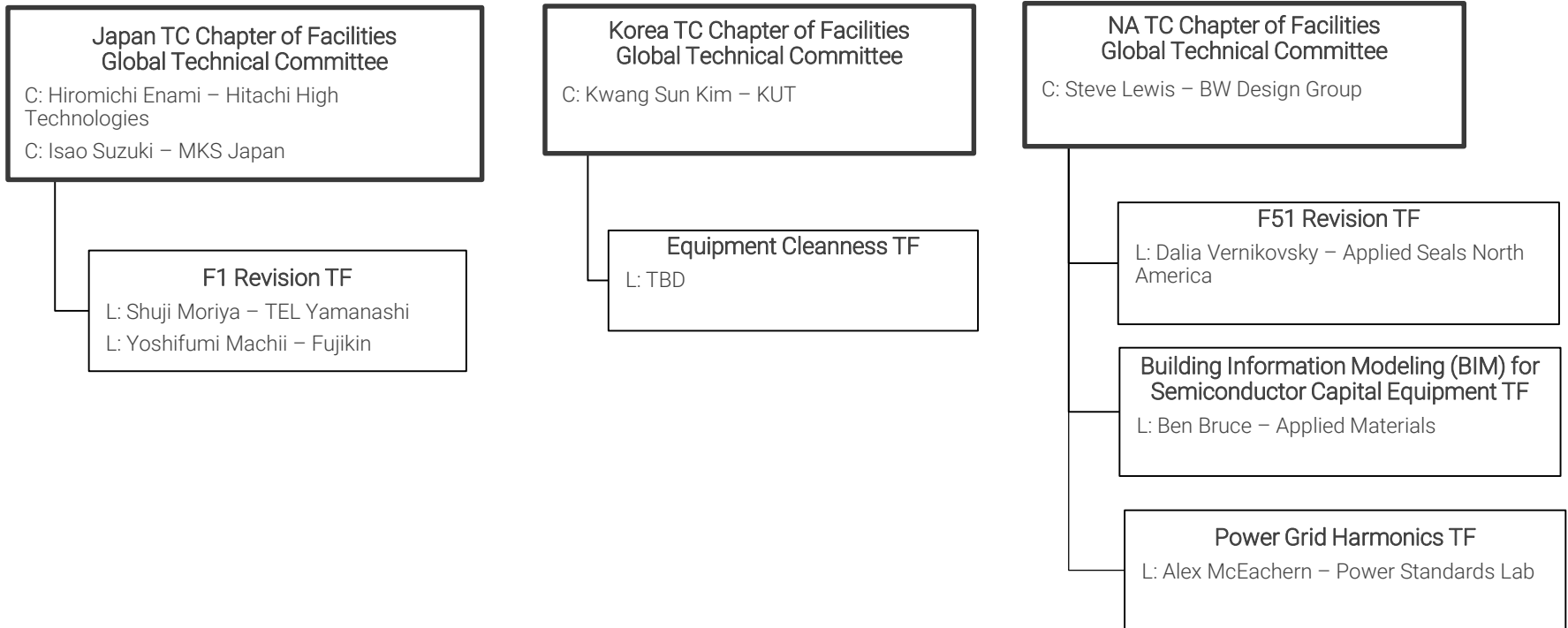
 = Global Task Force

Environmental, Health & Safety (EH&S) Global Technical Committee

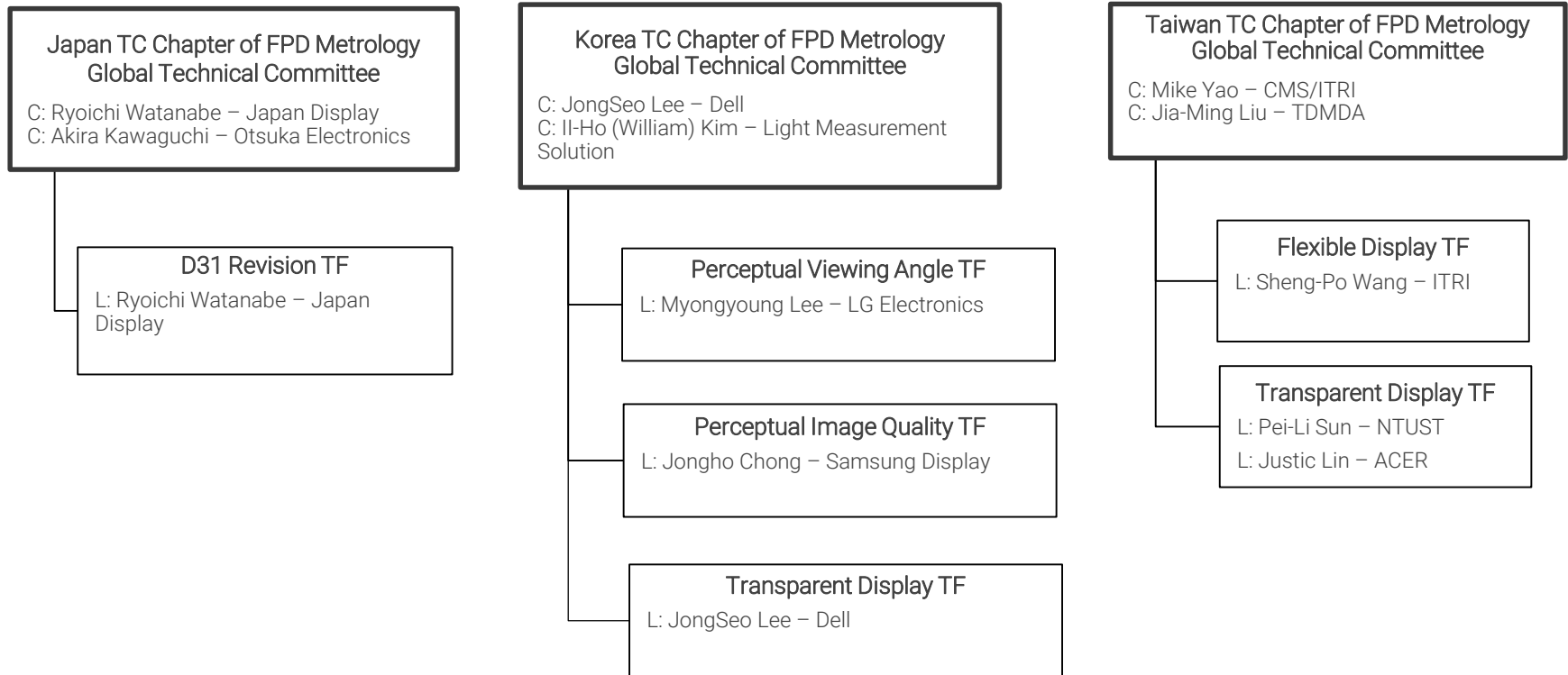


Facilities

Global Technical Committee



FPD Metrology Global Technical Committee



FPD Materials & Components Global Technical Committee

**Japan TC Chapter of FPD Materials & Components
Global Technical Committee**
C: Tadahiro Furukawa – Yamagata University
C: Yoshihiko Shibahara – Fujifilm

Flexible Display TF
L: Haruhiko Itoh – Teijin
L: Tadahiro Furukawa – Yamagata University

FPD Mask TF
L: Kazuya Shiojiri – SK Electronics
L: Hirofumi Ihara – HOYA

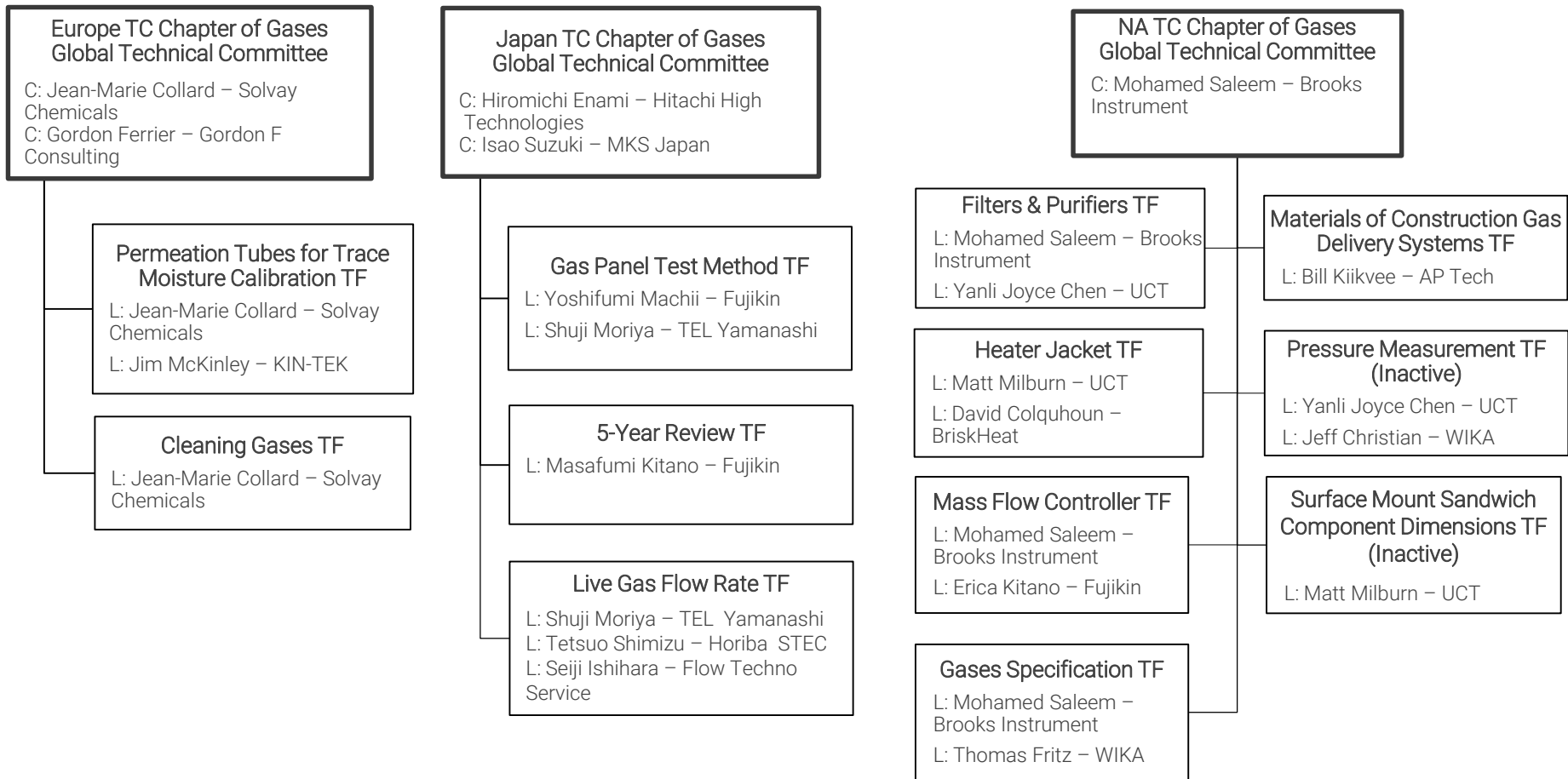
FPD Color Filter TF
L: Tadahiro Furukawa – Yamagata University

Polarizing Film TF
L: Yoshihiko Shibahara – Fujifilm
L: Motoshige Tatsumi – Nitto Denko

**Korea TC Chapter of FPD Materials & Components
Global Technical Committee**
C: JongSeo Lee – Dell
C: Il-Ho (William) Kim – Light Measurement Solution

Gases

Global Technical Committee



HB-LED Global Technical Committee

**China TC Chapter of HB-LED
Global Technical Committee**
 C: Yong Ji – Guizhou Haotian
 Optoelectronics Technology
 C: Weizhi Cai – San’an Optoelectronic

Korea HB-LED CFG
 L: HyeongSoo Park – SEMES
 L: Jong Hyeob Baek – KOPTI

**NA TC Chapter of HB-LED
Global Technical Committee**
 C: Iain Black – Philips
 C: Mike Feng – Silian
 C: Chris Moore – Frontier
 Semiconductor
 C: Andrew Kim – InnovationforX

Single Crystal Sapphire TF
 L: Yong Ji – Guizhou Haotian
 Optoelectronics Technology
 L: Xinhong Yang – AURORA

**Sapphire Single Crystal
Orientation TF**
 L: Songbin Zhao – DDXDF

**Sapphire Single Crystal
Ingot TF**
 L: Hongbo Zuo – AURORA

**Patterned Sapphire
Substrate TF**
 L: Jianzhe Liu – ECBO

**GaN based LED Epitaxial
Wafer TF**
 L: Jiangbo Wang – HC
 SemiTek

**Patterned Sapphire
Substrate (PSS) TF**
 L: Win Baylies – BayTech-
 Resor

**HB-LED Equipment
Communication Interfaces TF
(Inactive)**
 L: Brian Rubow – Cimatrix

**HB-LED Impurities & Defects
in Sapphire Wafers TF
(Inactive)**
 L: Luke Glinski – GT Advanced
 Technologies

**HB-LED Source Materials TF
(Korea)**
 L: Paul Ahn – Veeco
 L: H.B. Joo – Aixtron
 L: Sungjin Jun – LG Innotek
 L: Deok-gil – Samsung
 Electronics

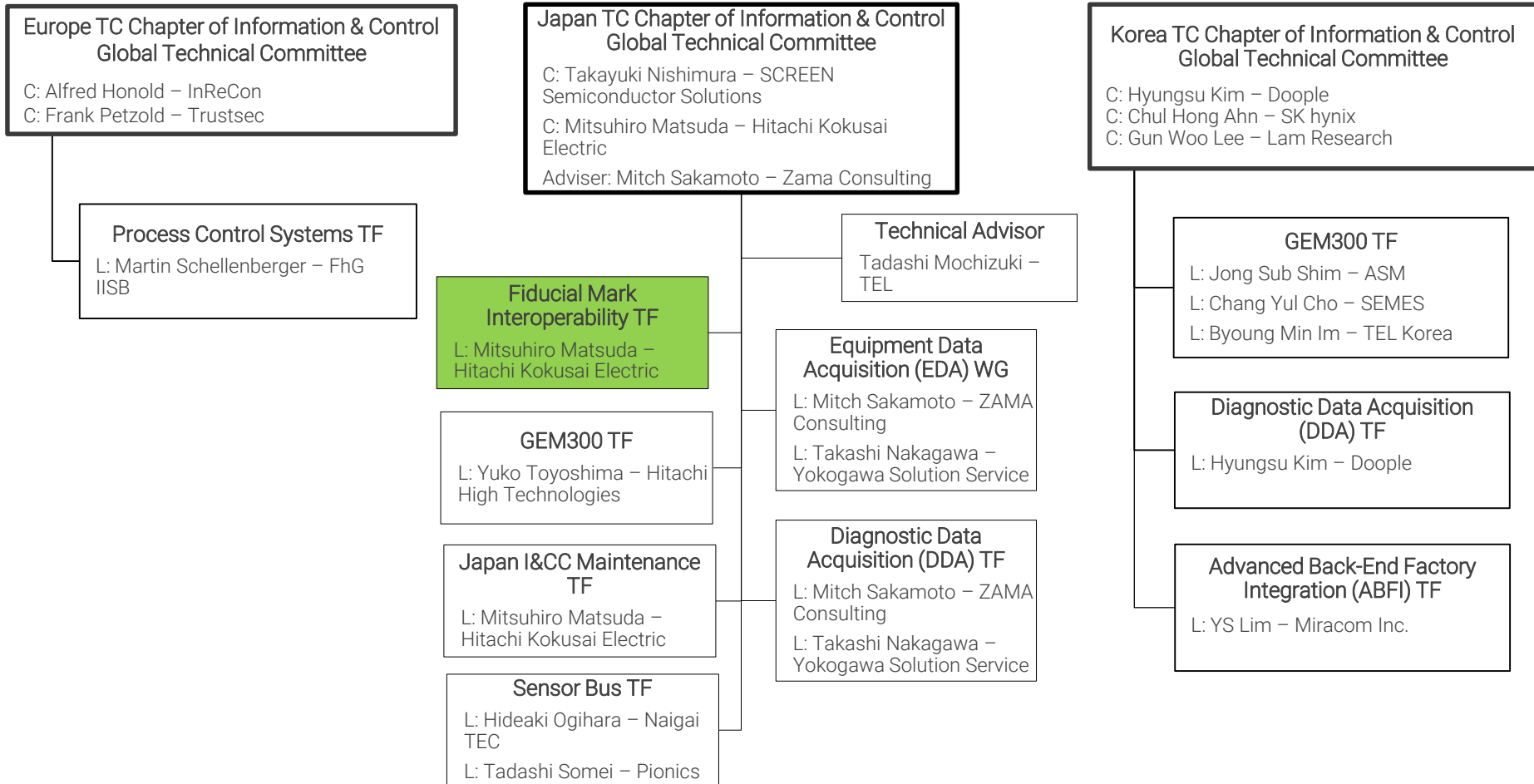
HB-LED Wafer TF
 L: Win Baylies – BayTech-
 Resor


HB-LED Assembly TF
 L: Paul Reid – Kulicke &
 Soffa

**HB-LED Equipment
Automation Interfaces TF
(Inactive)**
 L: Daniel Babbs – Brooks
 Automation
 L: Jeff Felipe – Entegris

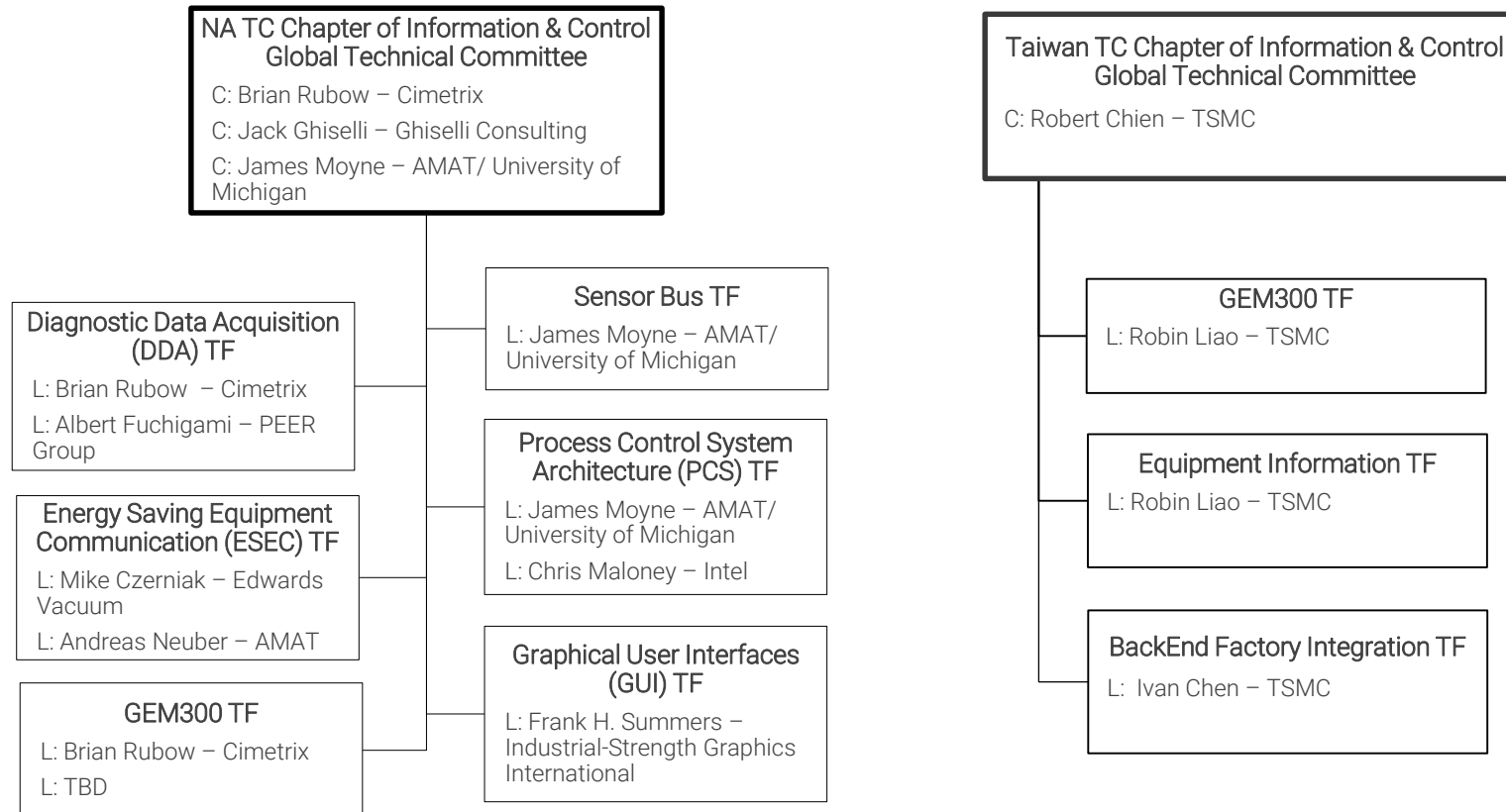
**Test Methods TF
(Inactive)**
 L: Peter Wagner – Self

Information & Control (I&C) Global Technical Committee

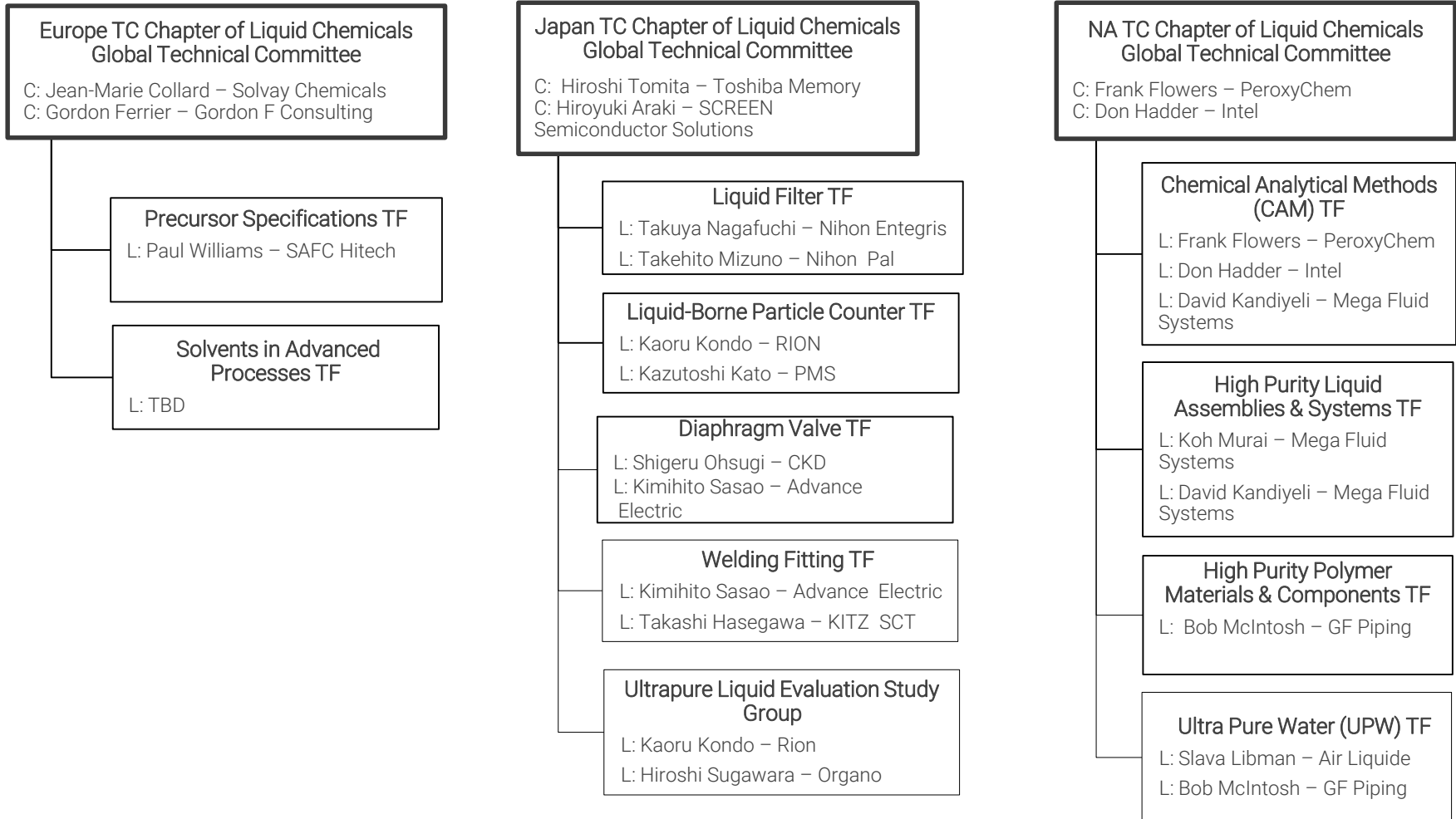


 = Global Task Force

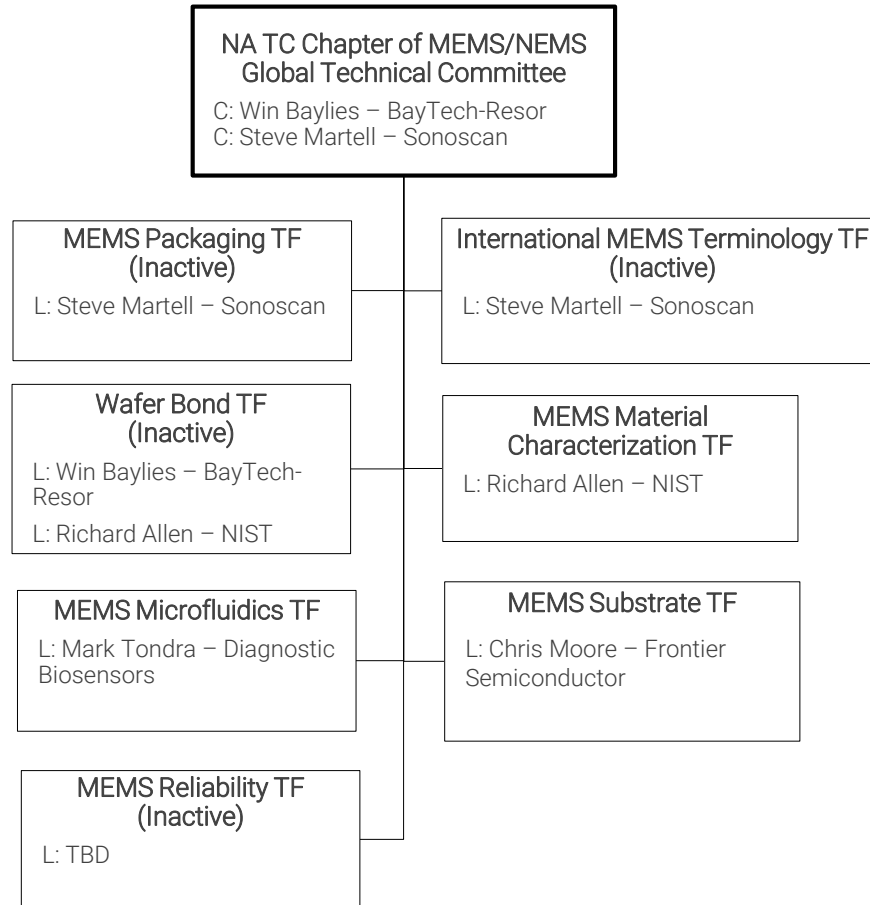
Information & Control (I&C) Global Technical Committee




Liquid Chemicals Global Technical Committee



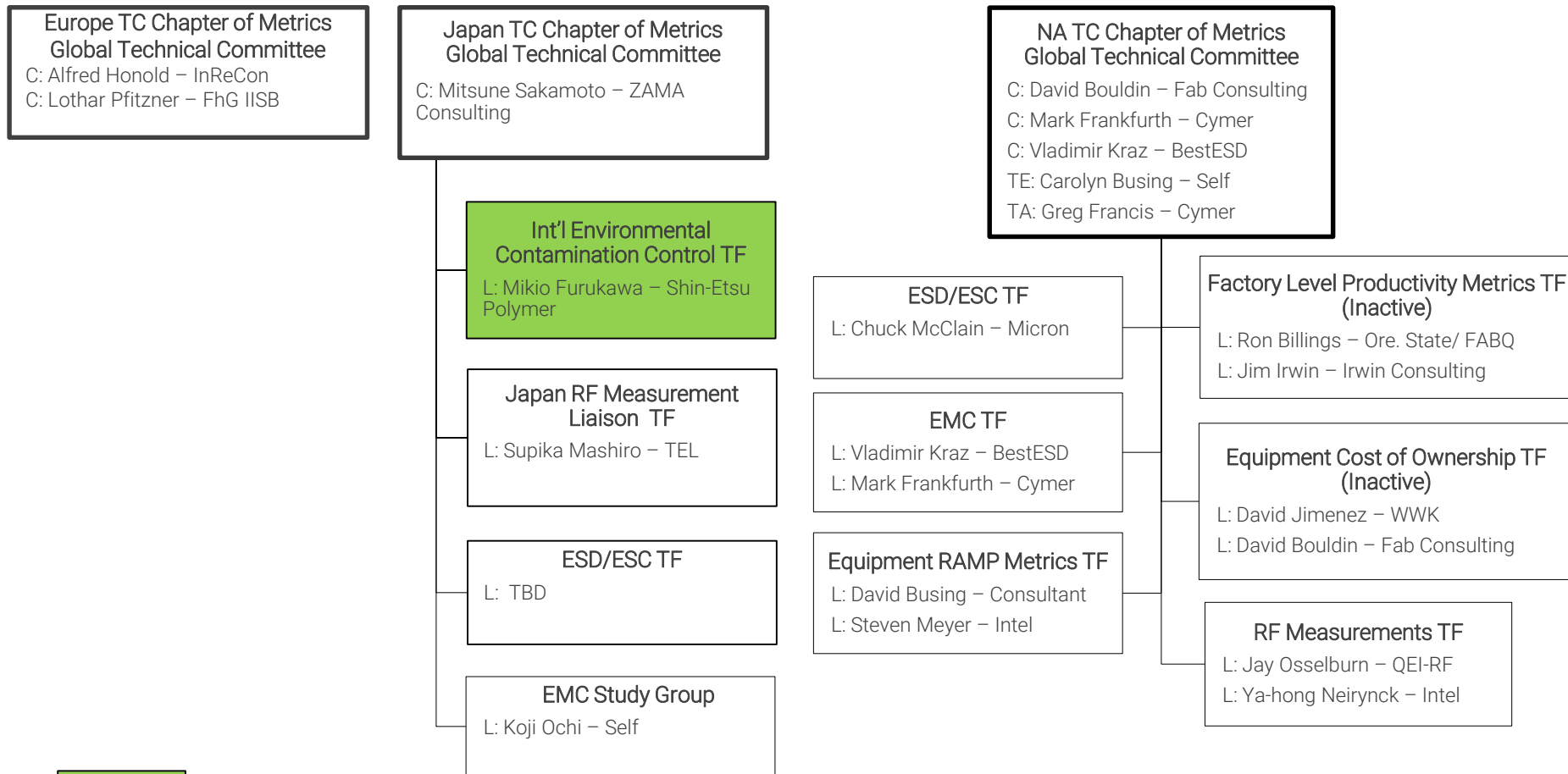
MEMS/NEMS Global Technical Committee




 = Global Task Force

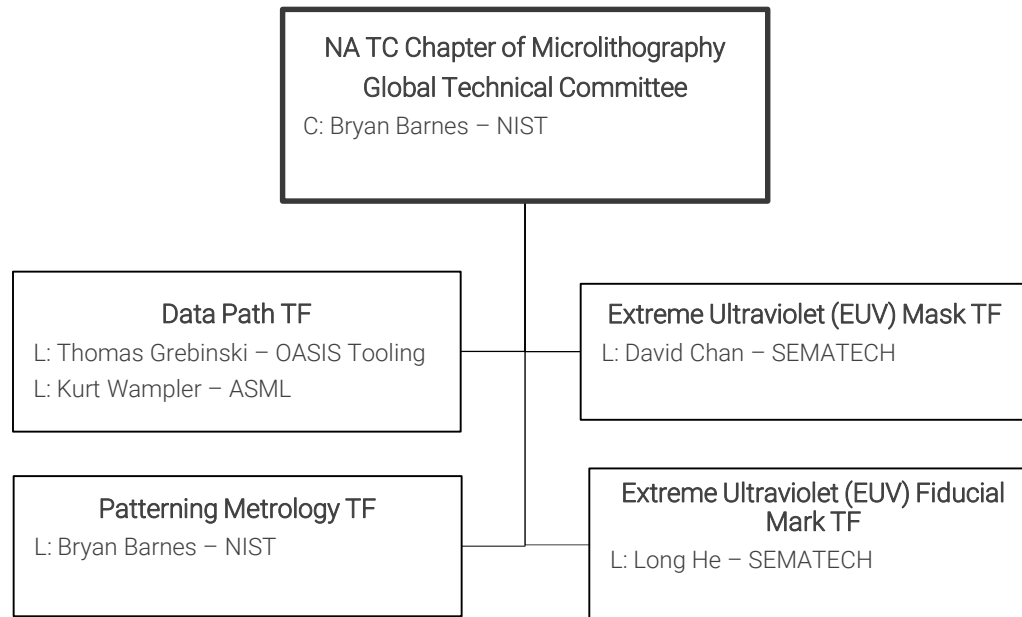
Metrics

Global Technical Committee

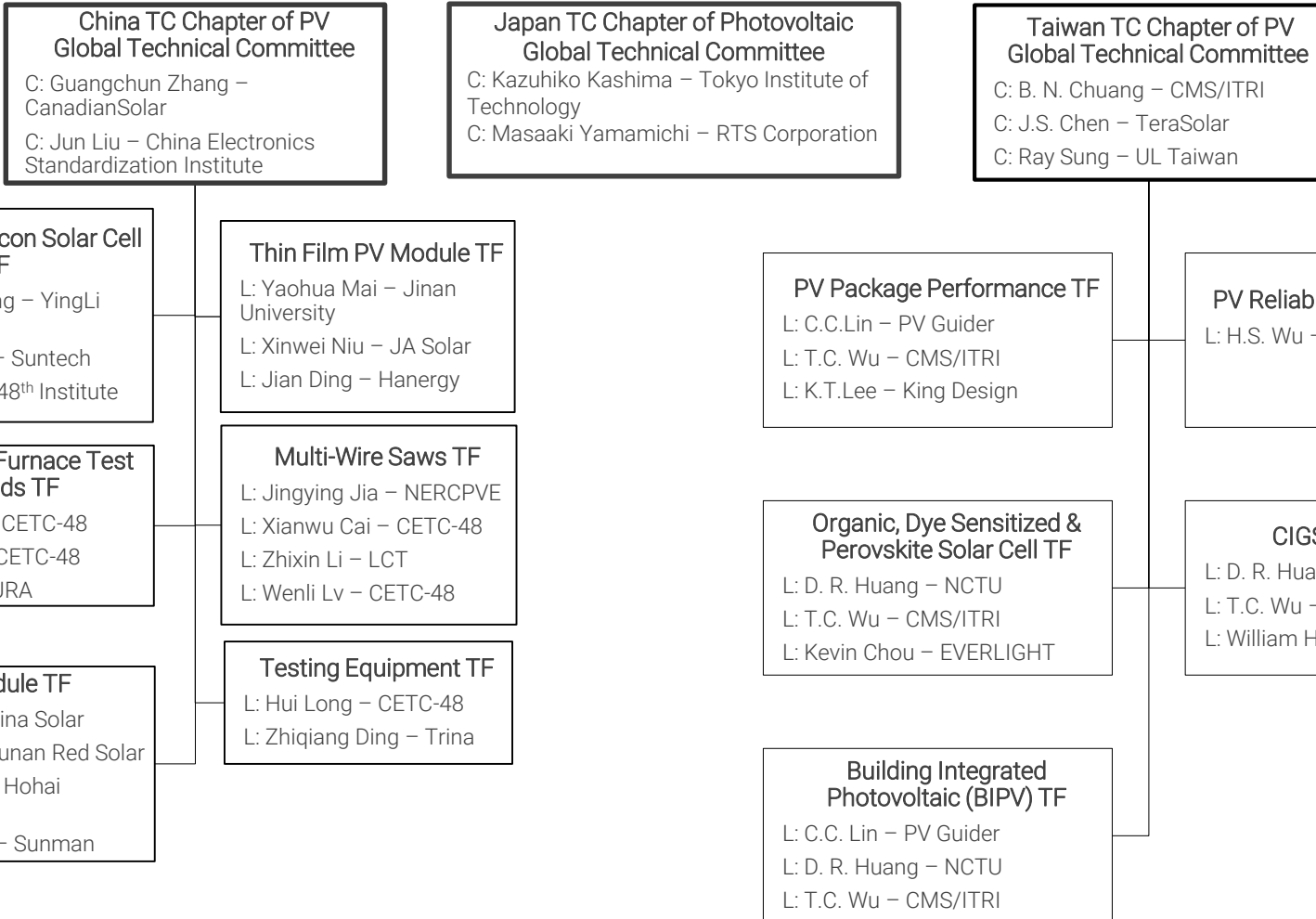


 = Global Task Force

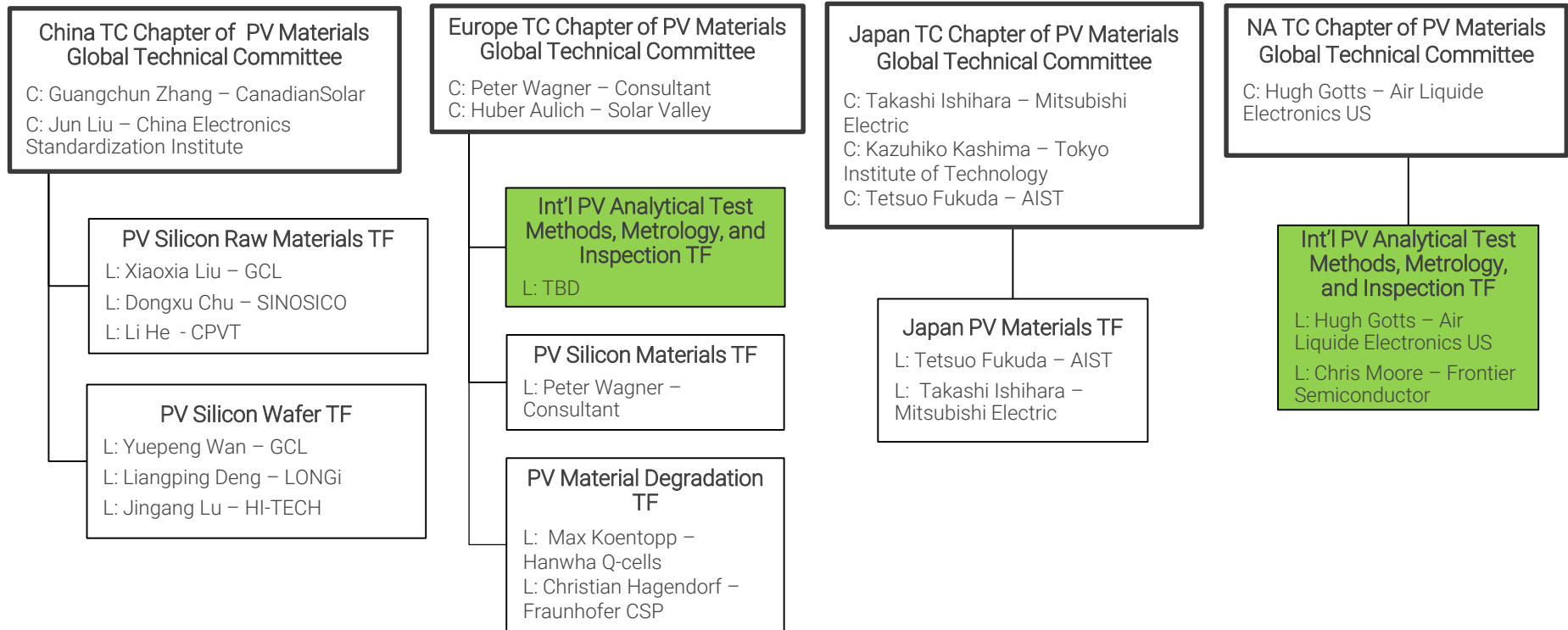
Micropatterning Global Technical Committee




Photovoltaic (PV) Global Technical Committee

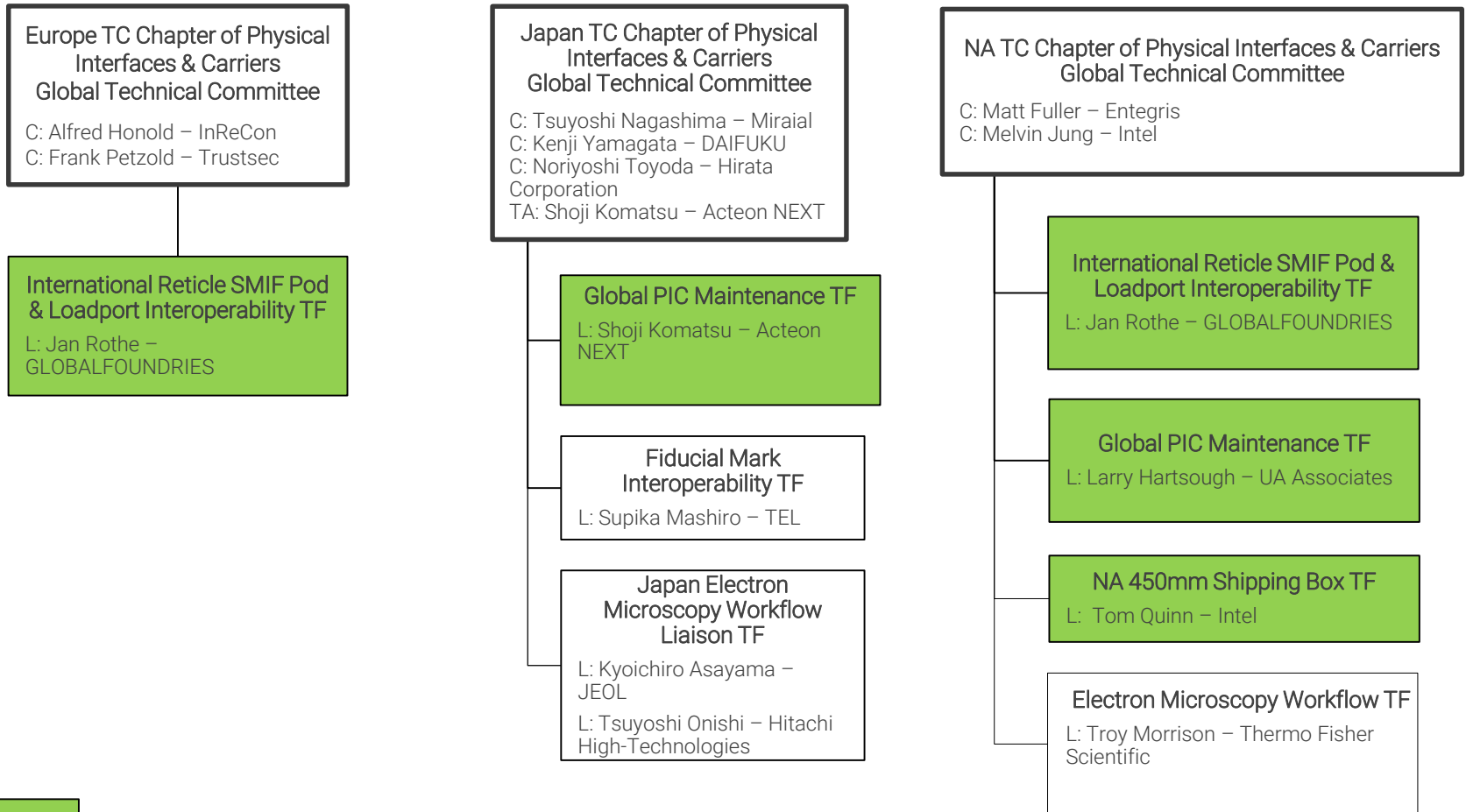



PV Materials Global Technical Committee



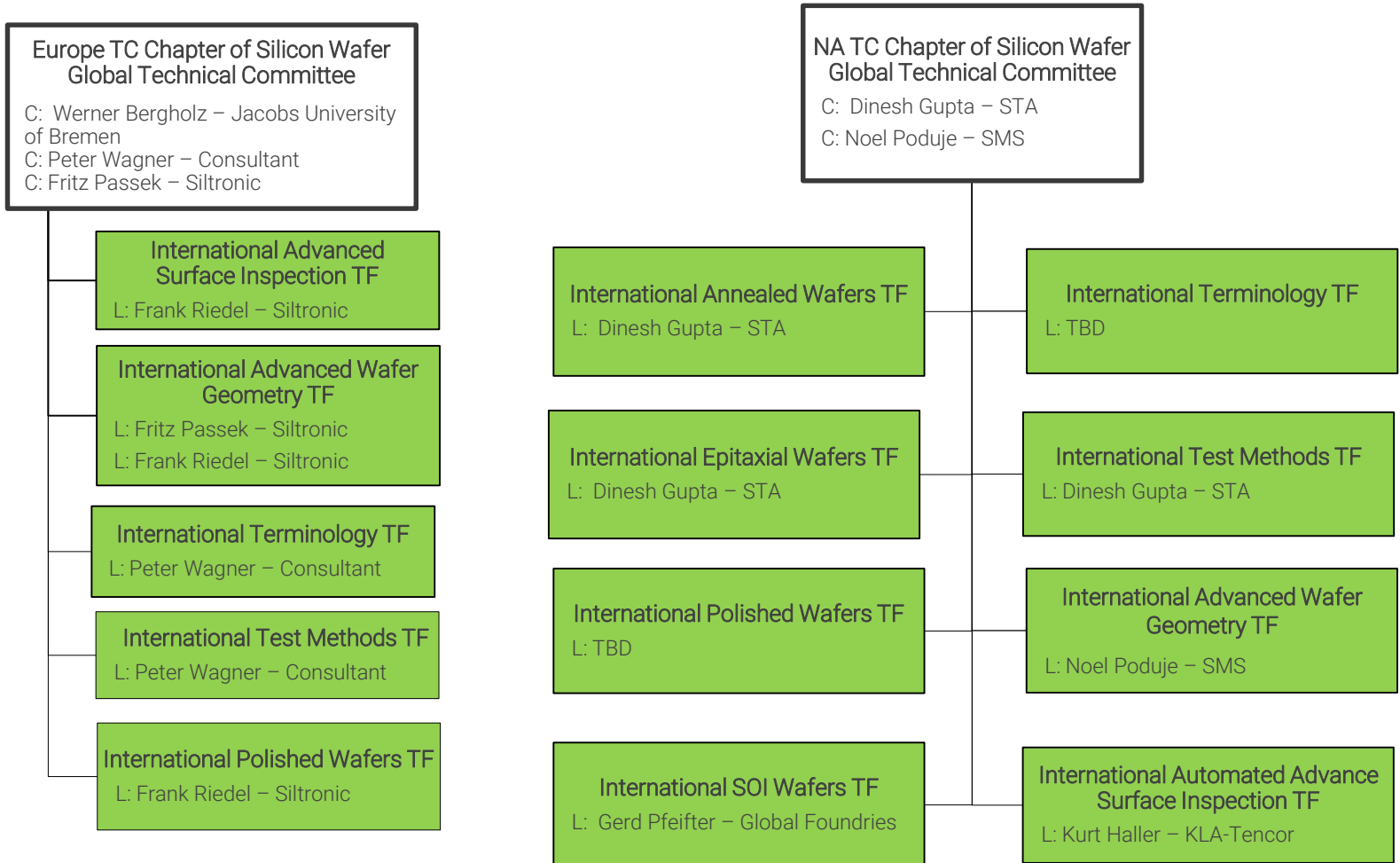
 = Global Task Force


Physical Interfaces & Carriers (PIC) Global Technical Committee



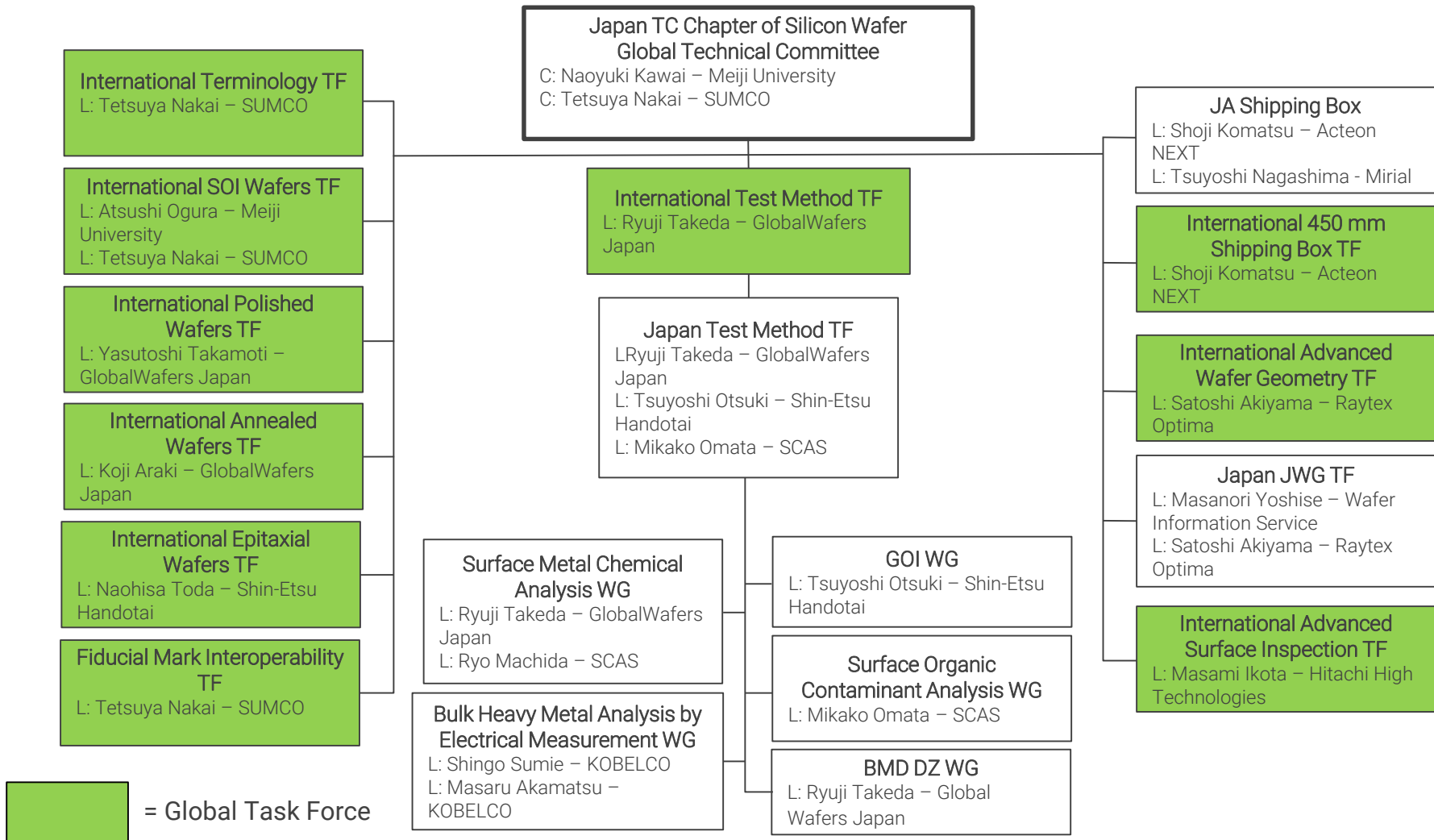
 = Global Task Force

Silicon Wafer Global Technical Committee

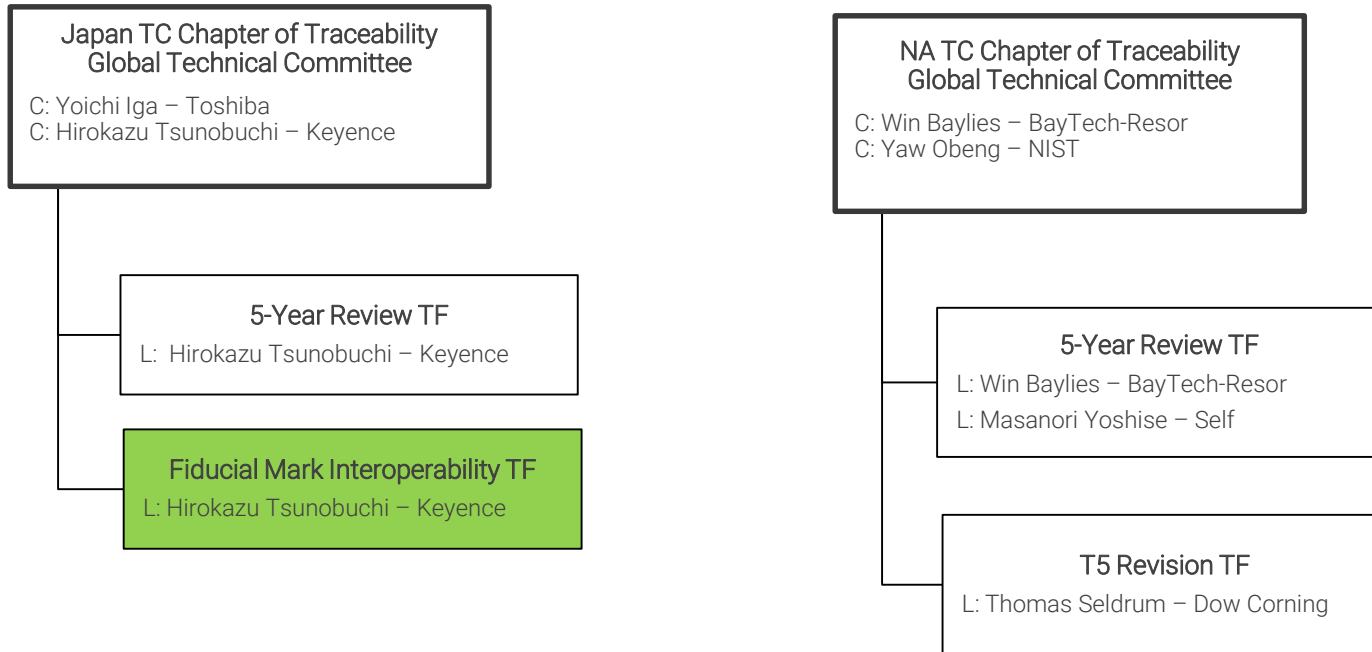



 = Global Task Force

Silicon Wafer Global Technical Committee



Traceability Global Technical Committee



 = Global Task Force